

A

B

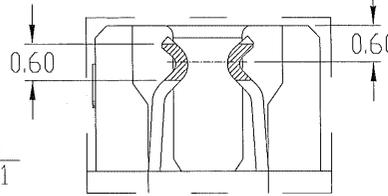
C

D

E

Function area
single side gold
plating

A
4:1



版次	ECN 编码	描述		设计/日期
X1	EL21070049	初版发行		苏琴_2021/07/15
		改前	改后	

NOTES: (Unless otherwise specified)

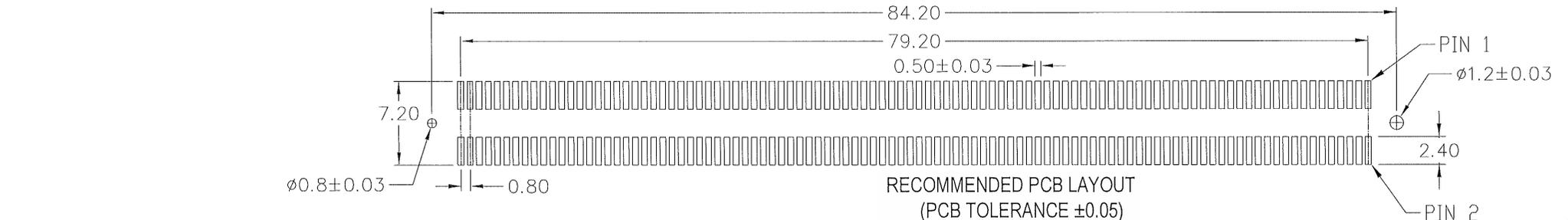
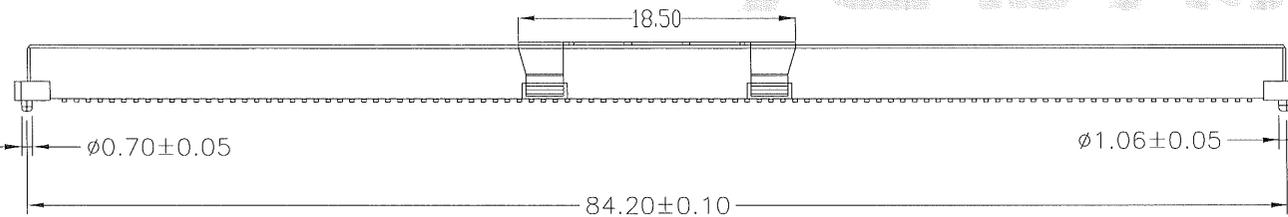
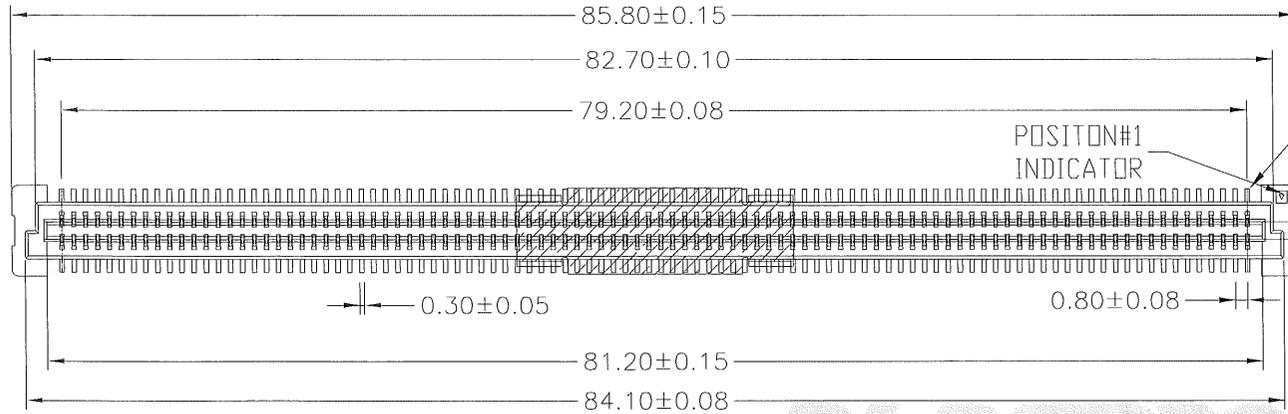
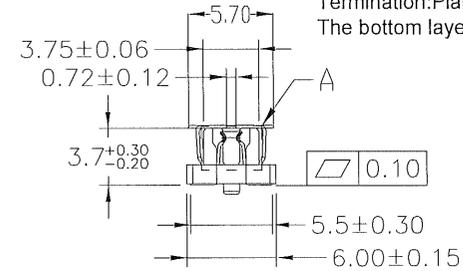
1. Dimension shall be interpreted per ANSI Y14.5M.
2. Materials:
Insulator material: High Temperature Thermoplastic, UL 94V-0; Color: Natural.
Contact material: Copper alloy.
3. Current Rating: 0.5A.
4. Voltage Rating: 50V AC/DC.
5. Working Temperature: -40°C ~ +105°C.
6. Harmful material should be compliant to doc. "EI-0005" standards.
7. Product number matrix:

DEAAA200BN00

B:MPAD+REEL

Plating Code:

Function area: Plating Au 10u" Min.
Termination: Plating matte Sn 100u" Min.
The bottom layer: Plating Ni 50u" Min.



RECOMMENDED PCB LAYOUT
(PCB TOLERANCE ±0.05)

	TOLERANCE TABLE		SCALE 2:1	DRAWN	苏琴	DATE 2021/07/15	DWG. NO. 600-0000-2237	TITLE	REV. X1
	X. ± 0.30	X.° ± 3°	UNIT mm	CHECK	李贵海	DATE 2021/07/15	PARTS NO.(INTENDED USE)		CUSTOMER DRAWING
	.X ± 0.25	.X° ± 2°	SIZE A4	APPROVE	苏琴	DATE 2021/07/15	DEAAA200BN00		
	.XX ± 0.20								

A

B

C

D

E